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ABSTRACT OF THE DISCLOSURE
INTEGRATED CIRCUIT TEST SOCKET

Disclosed is an improved integrated circuit socket having electrically conductive pads formed on a resilient circuitry component for contacting the terminals of an integrated circuit (IC) package which is positioned on the resilient circuitry. The electrically conductive pads are arranged around the center area of the resilient circuitry to be in one-to-one correspondence with the terminals of the IC package. The electrically conductive pads have individual circuit paths of substantially the same length and which are extending outwardly from the center area of the flexible circuitry, and additional electrically conductive pads are formed on the back side of the flexible circuitry in order to effect the required electrical connections to exterior circuits. These electrically conductive pads on the back side are connected to the conductor pattern on the front side by conductive through holes or vias. With this arrangement all conductors have the same, reduced inductance. An insulative apertured film is preferably positioned intermediate the IC package and the flexible circuitry having the electrically conductive pads in order to perform certain alignment and pressure application functions.

Fig. 1